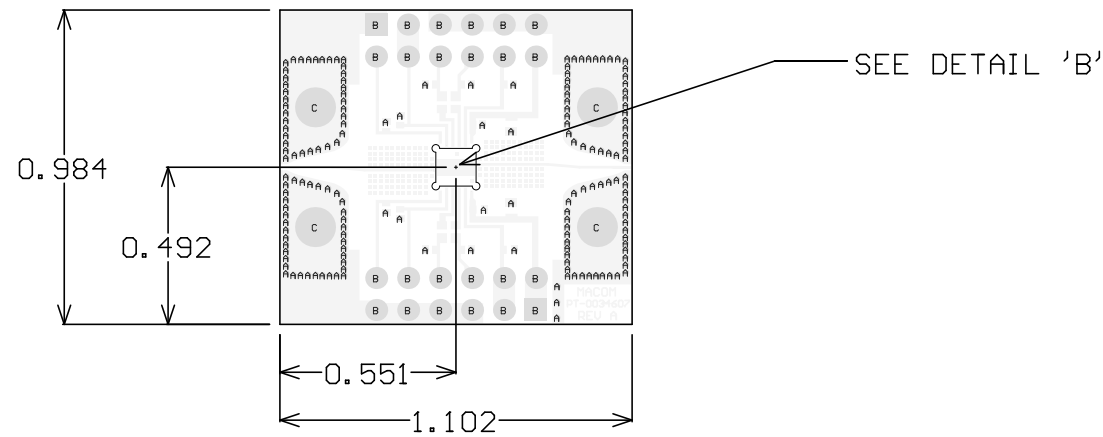


Symbol	Count	FHS	Tolerance	Plated	Hole Type	Drill Layer Pair
A	169	10.00mil	+3/-10mil	PTH	Round	Top Layer - Bottom Layer
B	24	39.37mil	+/-3mil	PTH	Round	Top Layer - Bottom Layer
C	4	78.00mil	+/-3mil	PTH	Round	Top Layer - Bottom Layer
	197 Total					

NOTES:

- MATERIAL:  
R04350B 4 MIL CORE, SEE DETAIL 'A'  
STARTING COPPER FOIL ON PRIMARY AND SECONDARY SIDE SHALL BE 1/2 OZ.  
COPPER ON PRIMARY AND SECONDARY SIDE TO BE PLATED UP AN ADDITIONAL 1/2 OZ CU.  
MATERIAL STACKUP AND THICKNESS PER DETAIL 'A'.
- PRIMARY AND SECONDARY SIDE FINISH:  
ELECTROLESS NICKEL/IMMERSION GOLD (ENIG) PER IPC-4552 LATEST REVISION.  
THERE SHALL BE NO PITS, PIN HOLES OR NODULES WITHIN EXPOSED METAL AREAS.
- PCB SHALL BE FABRICATED PER IPC-6012 CLASS 2 AND CONFORM TO IPC-A-600 CLASS 2 LATEST REVISIONS.
- ALL HOLES TO BE PLATED THRU UNLESS OTHERWISE SPECIFIED.  
ALL FINISHED DRILL HOLE SIZES APPLY AFTER PLATING.  
COPPER PLATING IN THROUGH HOLES WILL BE 0.001" AVERAGE WITH AN ABSOLUTE MINIMUM OF 0.0007".  
DIMENSIONS SHOWN ARE FOR LOCATION OF 0,0 FOR THE DRILL FILE.
- ELECTRONIC DATA IS EQUAL TO THE FINISHED LINE WIDTH.
- LPI SOLDER MASK COATING SHALL CONFORM TO IPC-SM-840, CLASS T.  
PRIMARY SIDE SOLDERMASK ONLY. COLOR-GREEN.
- NO SILKSCREEN ON PCB.
- RFIN AND RFOUT LINES TO BE 50 OHM +/-3 OHMS IMPEDANCE.
- GROUND FILL SHALL EXTEND TO BOARD EDGES UNLESS OTHERWISE NOTED.  
EXPOSED COPPER ON BOARD EDGE SHALL BE ACCEPTABLE.
- ALL MATERIALS DESCRIBED IN THIS DOCUMENT/DRAWING SHALL BE IN COMPLIANCE WITH AND CONTAIN NO SUBSTANCES RESTRICTED OR REQUIRING SPECIAL RECLAMATION UNDER THE LATEST RoHS, WEEE OR ELV DIRECTIVES.



PRIMARY LAYER